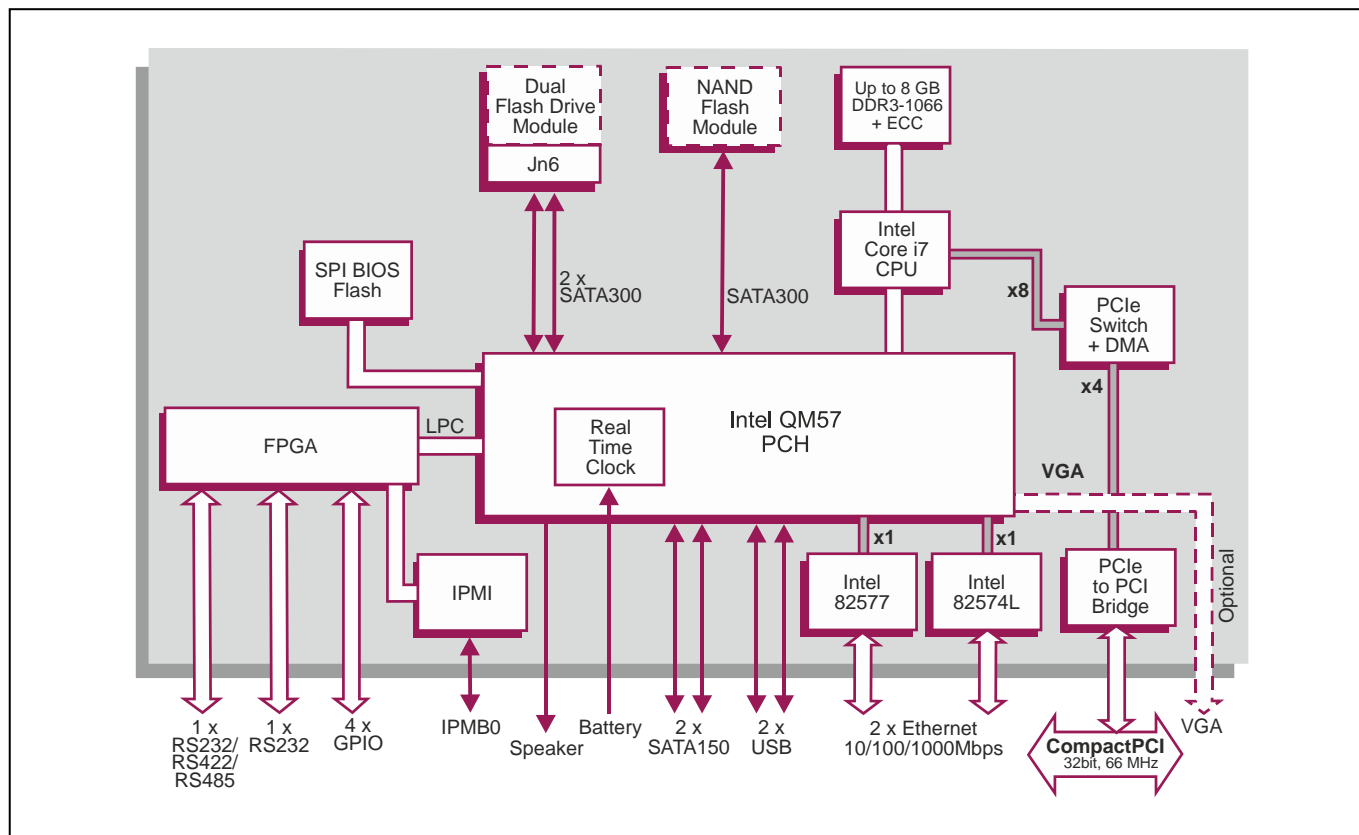


3U CompactPCI® board based on Intel® Core™ i7 Processor

Key Features

TP 702/38x is a high functionality 3U CompactPCI® board based on an Intel® Core™ i7 processor.

- Dual-core processor options for higher performance or lower power consumption
- Options for on-board solid state storage providing reliable operation
- Extended temperature and rugged conduction-cooled variants available
- Board Support Packages available for a number of standard Operating Systems



CompactPCI Computing Board

- 3U CompactPCI® board utilizing Intel® Core™ i7 processor
- for rugged versions, see separate datasheets:
 - rear plug compatible
 - conduction-cooled: TP 702/38x-RC
 - air-cooled: TP 702/38x-RA

Central Processor

- 2.53 GHz Intel® Core™ i7-610E processor, 2.0 GHz Intel® Core™ i7-620LE processor or 1.33 GHz Intel® Core™ i7-660UE processor
- common processor features are:
 - dual-core processor
 - 4 Mbytes shared last level cache
 - Intel® Hyper-Threading Technology
 - Intel® 64 Technology (64-bit computing)
 - Intel® Turbo Boost technology
- processor to DRAM memory, bus speed:
 - 610E - 1066MHz; 620LE - 1066MHz; 660UE - 800MHz
- Intel Turbo Boost technology allows faster graphics engine speed depending on the CPU loading
- utilizes Intel® Platform Controller Hub (PCH):
 - Mobile Intel® QM57 Express chipset

DRAM

- up to 8 Gbytes DDR3-1066 ECC SDRAM:
 - up to 8 Gbytes soldered on-board
 - single bit error correction
 - dual channel architecture
- accessible from processor or CompactPCI® bus

Mass Storage Interfaces

- 2 x SATA150 channels accessible via J2
- 1 x SATA300 channel routed to an optional 4 Gbytes NAND Flash Drive Module:
 - Flash drive write protect signal from backplane
- 2 x SATA300 channels to optional Dual Flash Drive Module:
 - one or two Flash Drives
 - uses XMC connectors (see Note 1)
 - Flash drive write protect switch on module

Ethernet Interfaces

- 2 x channels supporting:
 - 10BASE-T, 100BASE-TX, 1000BASE-T
 - implemented by an Intel® 82577 and an Intel® 82574L, via 2 x1 PCI Express® ports
 - both channels accessed via J2

Graphics Interface

- optional analog graphics accessed via J2:
 - integrated chipset graphics controller
- resolutions up to 1920 x 1200 @ 16M colors
- support for OpenGL 2.0, Windows® and Linux®

Serial Interfaces

- 2 serial interfaces accessible via J2
- 1 x RS-232 interface supporting Tx and Rx
- 1 x RS-232 interface supporting Tx, Rx, RI, CTS, RTS, DSR, DTR and DCD or 1 x RS-422/RS-485 supporting Tx and Rx
- 16550 compatible UARTs

Flash EPROM

- 8 Mbytes of BIOS Flash EPROM

Firmware Support

- UEFI-compliant BIOS with legacy mode support
- comprehensive Power-On Self-Test (POST)
- LAN boot firmware included

Software Support

- support for Linux®, Windows®, QNX®, Solaris® and VxWorks®

Optional Built-In Test (BIT) Support

- Power-on BIT (PBIT)
- Initiated BIT (IBIT)
- Continuous BIT (CBIT)

Other Peripheral Interfaces

- PC-compatible Real Time Clock
- long duration timer and watchdog timer
- option for legacy speaker interface via J2
- 2 x USB 2.0 interfaces, both accessed via J2
- external battery supply for RTC and BIOS data
- 4 x GPIO signals via J2
- CPU temperature monitor; voltages monitor; all accessible via IPMI

CompactPCI Interface

- universal signaling support, compliant with PICMG® 2.0 R3.0; 3.3V or 5V signaling levels
- 33/66 MHz; 32-bit interface accessed via J1
- PCI Express link from processor via PCIe-PCI bridge for off-board accesses:
 - DMA hardware support included
- operates as a System Slot controller (supporting up to 7 peripheral slots) or operates in a Peripheral Slot:
 - supports hot-swapping peripheral boards
 - PICMG 2.1 R2.0 Hot Swap Specification
- option to disable CompactPCI® interface (Satellite Mode):
 - receives power from CompactPCI bus
 - board can be hot swapped

IPMI

- PICMG 2.9 R1.0 (System Management Spec.):
 - implements the IPMB0 interface
- on-board Baseboard Management Controller
- supports 8 Kbytes of non-volatile memory

Safety

- PCB (PWB) manufactured with flammability rating of UL 94V-0

Electrical Specification

- +5V @ 3.1A (typical 2.0 GHz with 4 Gbytes DRAM)
- +3.3V @ 5.1A
- voltages +5%/-3%
- +12V and -12V not required

Environmental Specification

- operating temperatures:
 - 0°C to +55°C (N-Series)
 - -25°C to +70°C (E-Series: 2.0 GHz or 1.33 GHz)
 - -40°C to +85°C (K-Series: 1.33 GHz)
- non-operating temperature: -40°C to +85°C
- 5% to 95% Relative Humidity, non condensing:
 - K-Series includes humidity sealant

Mechanical Specification

- 3U form-factor:
 - 3.9-inches x 6.3-inches (100mm x 160mm)
- single slot
- connectors: IEC-1076-4-101 for J1-J2
- shock: 20g, 11ms, ½ sine
- vibration: 5Hz-2000Hz at 2g, 0.38mm peak displacement

I/O Compatible with the TP 402/35x

- rear I/O compatible with the legacy TP 402/35x

Note 1: The XMC connectors are provided for the Dual Flash Drive Module only. The CPU heatsink for air-cooled boards can not support an XMC module. The conduction-cooled board (RC-Series) can support an optional XMC module (see TP 702/38x-RC datasheet)